

Claims 1-20 were rejected as being unpatentable over Eldridge in view of Pylkki. The rejection states in part:

[I]t would have been obvious ... to modify the device of Eldridge et al. by replacing the contact devices 2118 by a V shape contact device 50 of Figures 1 and 3 as taught by Pylkki et al. because the V-shape contact device provide for a minimum pitch between contact, also conventional bonding machines are routinely tested at this minimum spacing, and thereby statistics can be readily obtained to assess the variances of this process for a given bonding machine, or for different bonding wire materials.

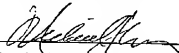
Applicant respectfully disagrees.

Eldridge relates to microsprings for integrated circuit testing as described above. Pylkki, however, is directed to far different subject matter. Pylkki relates to a scanning probe microscope for thermal imaging. Note that the V-shaped probes of Pylkki include a thermal sensor, shown in greater detail in Figure 4 of Pylkki.

Although functional testing of integrated circuits (Eldridge) and thermal imaging of integrated circuits (Pylkki) may both be applied to the same article, these two disciplines are otherwise quite separate and distinct. Hence, it would not have been obvious to combine the teachings of Pylkki with those of Eldridge in the manner described.

Withdrawal of the rejection and allowance of claims 1-20 is respectfully requested.

Respectfully submitted,


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